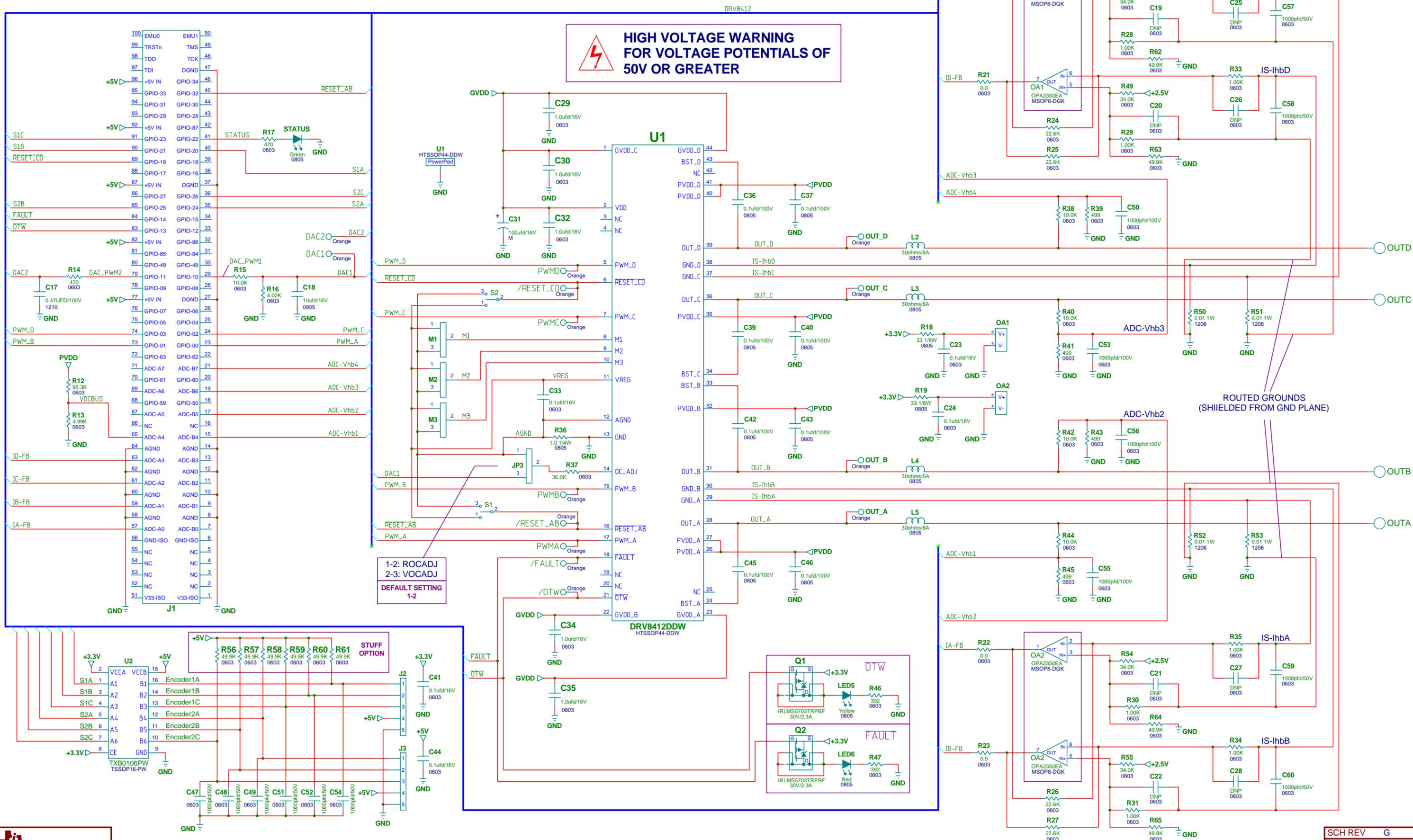


DRV8412DDW EVALUATION BOARD REV G

HIGH VOLTAGE WARNING FOR VOLTAGE POTENTIALS OF 50V OR GREATER



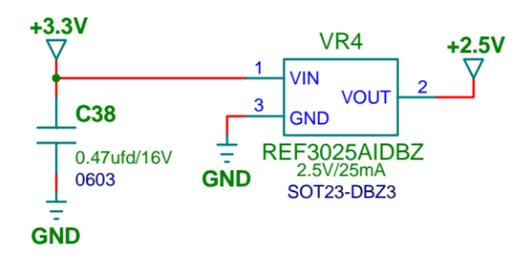
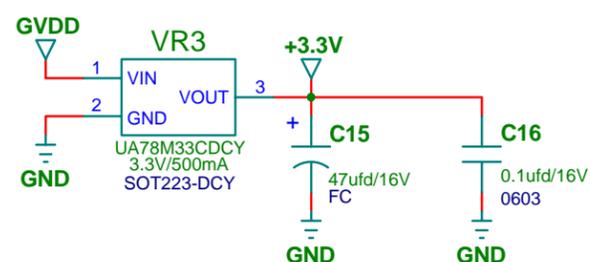
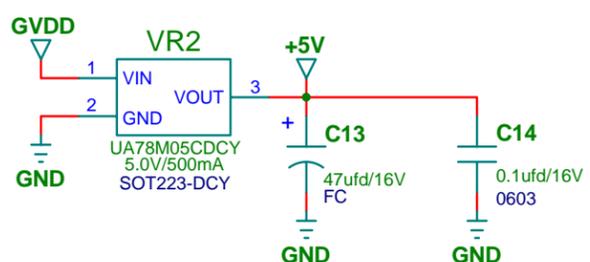
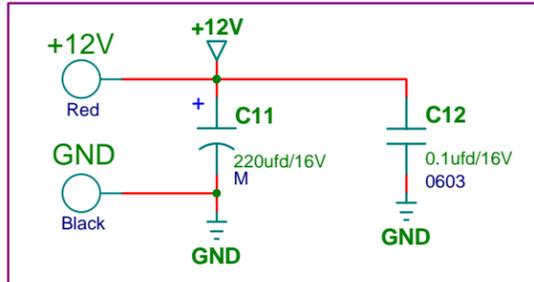
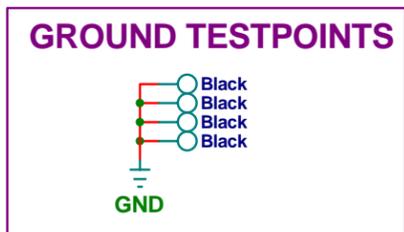
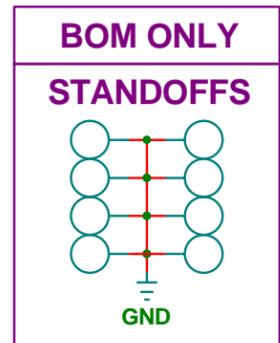
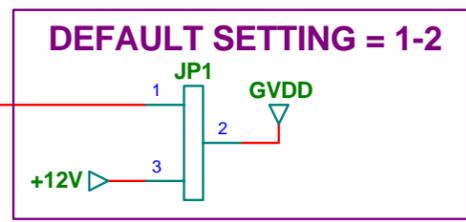
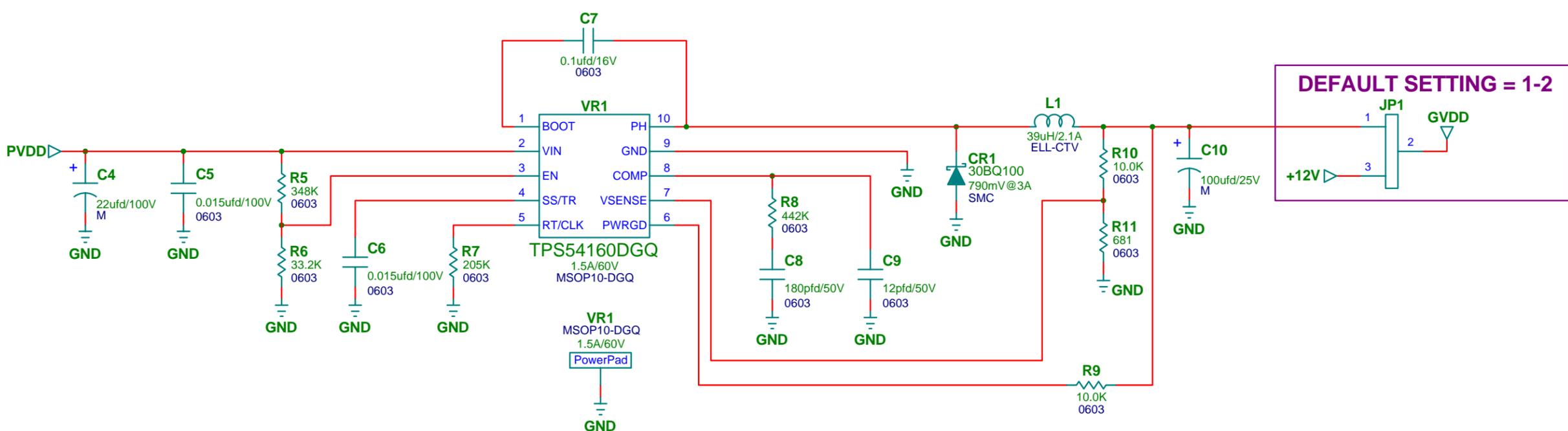
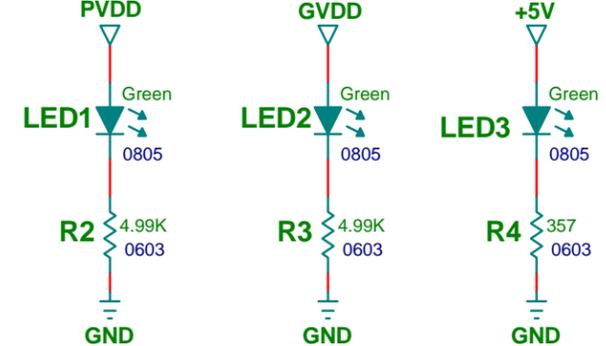
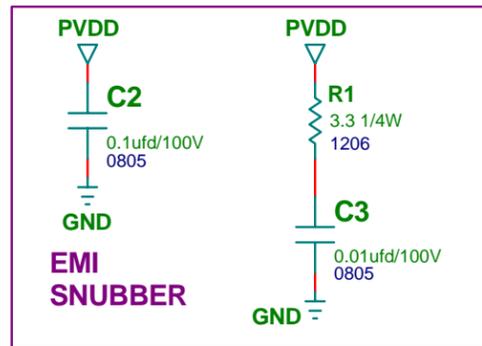
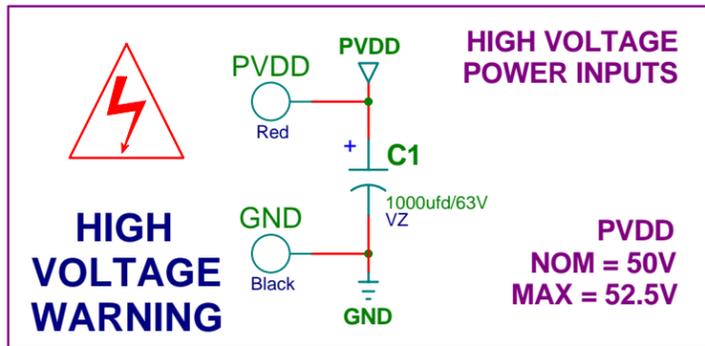
1-2: ROCADJ
2-3: VOCADJ
DEFAULT SETTING 1-2

ROUTED GROUNDS (SHIELDED FROM GND PLANE)



DRV8412DDW EVALUATION BOARD

REV G



REVISION HISTORY PAGE 1

REVISION	DESCRIPTION	DATE	APPROVAL
A	INITIAL RELEASE	APRIL 23, 2009	ML
B	PCB EDITS ONLY, NO SCHEMATIC CHANGES	MAY 13, 2009	ML
C	<ol style="list-style-type: none"> 1. REMAPPED INPUT CONNECTOR, J1. 2. ADDED 5V VOLTAGE REGULATOR CIRCUIT. 3. DELETED R5, R6, R8, R9, R10, R11, R12, R13 AND R14. 4. DELETED R16. 5. RENAMED AGND TO GND. (PIN 12) 6. CONNECTED PIN 12 TO GND. 7. EDITED MODE SELECTION MATRIX. 8. CHANGED C11 TO 22UFD/16V. 9. CHANGED C12 TO 1.0UFD/16V. 	July 13, 2009	ML
D	<ol style="list-style-type: none"> 1. RENUMBERED U2 TO U1. 2. RENUMBERED J6 TO J2. 3. CHANGED C4 TO FC 330UFD/16V. 4. CHANGED C11 TO FC 47UFD/16V. 5. CHANGED C12 TO 0603/0.1UFD/16V. 6. CHANGED C15/18/20/23 TO 0805/0.1UFD/100V. 7. ADD R7, 1 OHM 0805 1/4W, BETWEEN AGND AND GND. 	OCTOBER 30, 2009	ML
E	<ol style="list-style-type: none"> 1. ADDED DIMM SOCKET FOR CC8250 BOARD. 2. MOVED M1-3, M2-3, M3-3 TO AGND. 3. ADDED PVDD TO 5V SWITCHER CIRCUIT. 4. ADDED 1.25V VOLTAGE REGULATOR. (VR3) 5. CHANGED JST CONNECTORS TO BANANAS. 6. ADDED JUMPER FOR OC-ADJ. 7. ADDED ENCODER HEADERS. 	DECEMBER 21, 2009	ML
F	<ol style="list-style-type: none"> 1. MOVED RESET_AB LINE TO J1-89. 2. CHANGED R48/R49/R54/R55 TO 49.9K OHMS. 3. CHANGED R28/R29/R30/R31/R32/R33/R34/R35 TO 1.00K OHMS. 4. CONVERTED 1.25V TO 2.5V. 5. ADDED R62/R63/R64/R65 TO OA1/2 PINS 3/5. VALUE = 49.9K OHMS. 6. CORRECTED PART NUMBER FOR VR1 7. CHANGED VR4 TO 2.5V VOLTAGE REFERENCE. 8. CHANGED C19/C20/C21/C22/C25/C26/C27/C28 TO DNP. 9. CHANGED C5 AND C6 TO 100V. 10. CHANGED C4 TO 22UFD/100V. 	NOVEMBER 4, 2010	KM

REVISION HISTORY PAGE 2

REVISION	DESCRIPTION	DATE	APPROVAL
G	1. CHANGED R24-R27 TO 0603-22.6K OHMS. 2. CHANGED R48, R49, R54 AND R55 TO 0603-34.0K OHMS. 3. CHANGED R56-R61 TO 0603-49.9K OHMS. 4. CHANGED R37 TO 36K OHMS.	JANUARY 26, 2011	RK

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